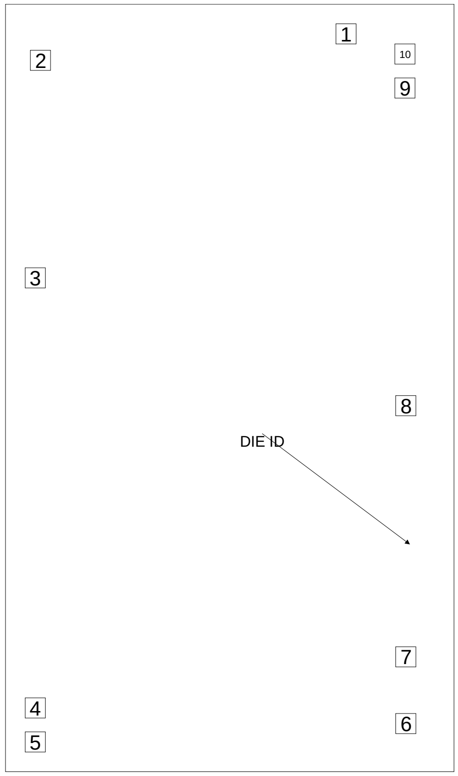
National Semiconductor
The Sight & Sound of Information

LM6172 MDR
DUAL HIGH SPEED, LOW POWER, LOW DISTORTION VOLTAGE FEEDBACK

19-Jan-2012

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM6172C	Bond Pad Opening Size (min)	80.00µm x 80.00µm
Die Step	C	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1778.00µm x 3048.00µm 70.0mils x 120.0mils	Back Side Connection	Floating
Thickness	304.8µm Nominal		
Min Pitch	135.00µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(C-Step) (Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
OUTPUT A	1	461.00	1406.00	80.00	x	80.00
INPUT A-	2	-750.50	1301.00	80.00	x	80.00
INPUT A+	3	-771.00	437.00	80.00	x	80.00
V-	4	-771.00	-1271.00	80.00	x	80.00
V-	5	-771.00	-1406.00	80.00	x	80.00
INPUT B+	6	698.00	-1333.00	80.00	x	80.00
INPUT B-	7	698.00	-1068.00	80.00	x	80.00
OUTPUT B	8	698.00	-70.50	80.00	x	80.00
V+	9	694.50	1191.00	80.00	x	80.00
V+	10	694.50	1326.00	80.00	x	80.00

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Notes

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